

SMART 2019

8-12 July 2019, Paris, France

How to register and submit contributions

Authors are invited to submit individual contributions on any of the conference topics. Submissions and conference registration should be performed electronically via the conference website:

<http://congress.cimne.com/SMART2019>

Conference Secretariat

International Centre for Numerical Methods in Engineering

CIMNE Congress Bureau

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Location

The ECCOMAS Thematic Conference on Smart Structures and Materials (SMART 2019) will be organized in Paris.



Registration Fees

Authors are invited to create their online accounts and register for the abstracts and full papers submissions and registrations fees payments. Depending on the author category and payment timing, the following fees (in Euro only) apply:

	Reduced fees If paid by April 29, 2019	Full fees If paid until May 27, 2019
Delegates	550€	650€
PhD students	400€	450€
Accompanying persons	150€	200€

ECCOMAS members will have a 5% reduction on the delegate fees.

Registration fee include: attending all sessions, welcome reception, coffee breaks, lunches, banquet dinner, program, book of abstracts and e-proceedings.

Accompanying persons' fees include the welcome reception, banquet dinner and other programmed social events.

SMART 2019

IX ECCOMAS Thematic Conference on
Smart Structures and Materials

8-12 July 2019, Paris, France



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About Smart 2019

The 9th ECCOMAS Thematic Conference on Smart Structures and Materials (SMART 2019) will be organized in Paris, at the Arts et Métiers – Ensam (Paris Campus). This conference series has started in 2003 and progressed successfully over the years. Its previous editions were held in Poland (2003, 2007), Portugal (2005, 2009, 2015), Germany (2011), Italy (2013) and Spain (2017).

SMART 2019 will aim at providing a comprehensive forum for discussing current state of the art in the field of smart structures and materials as well as at developing future ideas on a multidisciplinary level.

The conference is one of the Thematic Conferences of the European Community on Computational Methods in Applied Sciences (ECCOMAS).



Conference Chairmen

Prof. Ayech Benjeddou, SUPMECA - ROBERVAL (Sorbonne Universités-UTC/CNRS), France

Dr. Habil. Nazih Mechbal, Arts et Métiers – Ensam (HESAM Université), France

Prof. Jean-François DEÜ, Conservatoire national des arts et métiers (HESAM Université), France

International Scientific Committee

- A. Araujo, IDMEC – Instituto Superior Tecnico, Portugal
- A. Benjeddou, SUPMECA – ROBERVAL (UTC/CNRS), France
- T. Ben Zineb, Université de Lorraine, France
- C. Boller, Universität des Saarlandes, Germany
- E. Carrera, Politecnico di Torino, Italy
- S. Casciati, Università di Catania, Italy
- A. Cunha, Universidade do Porto, Portugal
- J.-F. Deü, Conservatoire national des arts et métiers, France
- A. Güemes, Universidad Politécnica de Madrid, Spain
- J.B. Høgsberg, Danmarks Tekniske Universitet, Denmark
- J. Holnicki-Szulc, Polish Academy of Sciences, Poland
- M. Krommer, Technische Universität Wien, Austria
- G. Kulikov, Tambov State Technical University, Russia
- R. Lammering, Universität der Bundeswehr Hamburg, Germany
- N. Mechbal, Arts et Métiers – Ensam, France
- W. Ostachowicz, Polish Academy of Sciences, Poland
- O. Polit, Université Paris Nanterre, France
- J. Rodellar, Universitat Politècnica de Catalunya, Spain
- D. Saravanos, University of Patras, Greece

Conference Topics

General Topics:

- **Smart structures** (fundamentals, concepts, design, modelling, simulation, testing, analysis, etc.)
- **Smart materials** (piezoelectric, shape memory, magneto/electro-rheological, magneto/electro-strictive, nano-reinforced, biomimetic, optic, characterization, homogenization, etc.)
- **Smart systems** (micro, nano, mechatronic, robotic, automation, integration, packaging, etc.)
- **Structural control** (active/semi-active/hybrid, sensors/actuators, noise, damping, morphing, etc.)
- **Health monitoring** (sensor/actuator networks, wireless communication, energy harvesting, etc.)
- **Manufacturing technology** (bonding, embedding, connection, additive, printing, painting, etc.)
- **Engineering applications** (mechanical, aeronautic, automotive, civil, bio-mechanics/medical, etc.)

Important Dates

Authors are invited to observe the following deadlines for:

Abstracts submissions	February 1, 2019
Full papers submissions & Reduced fees registrations	April 29, 2019
Full fees registrations	May 27, 2019

